XN05531 (XN5531)

Silicon NPN epitaxial planar type

For high-frequency/oscillation/mixing

■ Features

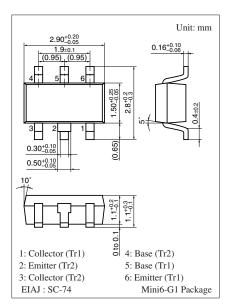
- Two elements incorporated into one package
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

• 2SC3130 × 2

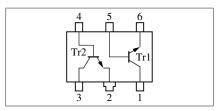
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	15	V	
Collector-emitter voltage (Base open)	V _{CEO}	10	V	
Emitter-base voltage (Collector open)	V_{EBO}	3	V	
Collector current	I_C	50	mA	
Total power dissipation	P_{T}	200	mW	
Junction temperature	T_j	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



Marking Symbol: 5M

Internal Connection



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	10			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \ \mu A, I_C = 0$	3			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 10 \text{ V}, I_{E} = 0$			1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 10 \text{ V}, I_{B} = 0$			10	μΑ
Forward current transfer ratio	h_{FE}	$V_{CE} = 4 \text{ V}, I_C = 5 \text{ mA}$	75	200	400	_
h _{FE} ratio	h _{FE(Small} *1 /Large)	$V_{CE} = 4 \text{ V}, I_C = 5 \text{ mA}$	0.50	0.99		_
	Δh _{FE} *2	h_{FE2} : $V_{CE} = 4 \text{ V}$, $I_{C} = 100 \mu\text{A}$	0.75		1.60	
		h_{FEI} : $V_{CE} = 4 \text{ V}$, $I_C = 5 \text{ mA}$				
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 20 \text{ mA}, I_B = 4 \text{ mA}$			0.5	V
Transition frequency	f_T	$V_{CB} = 4 \text{ V}, I_{E} = -5 \text{ mA}, f = 200 \text{ MHz}$	1.4	1.9	2.5	GHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 4 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.9	1.1	pF
Reverse transfer capacitance (Common base)	C _{rb}	$V_{CB} = 4 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.25	0.35	pF
Collector-base parameter	r _{bb} ' • C _C	$V_{CB} = 4 \text{ V}, I_{E} = -5 \text{ mA}, f = 30 \text{ MHz}$		11.8	13.5	ps

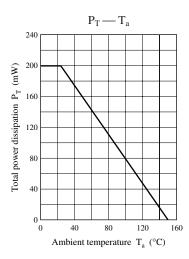
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

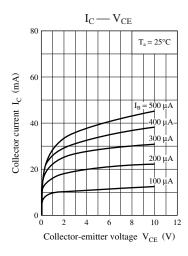
2. *1: Ratio between 2 elements

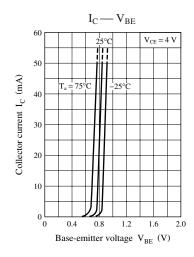
*2: $\Delta h_{FE} = h_{FE2} / h_{FE1}$

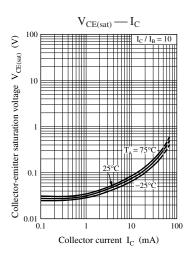
Note) The part number in the parenthesis shows conventional part number.

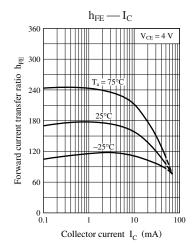
Panasonic

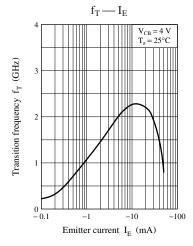


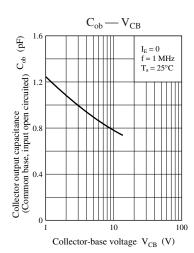












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